SCOPE:

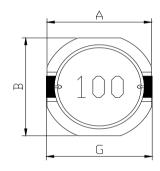
This specification applies to the Pb Free high current type SMD inductors for MSCDRI-6030LC-SERIES

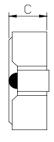
PRODUCT INDENTIFICATION

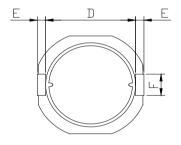
MSCDRI - 6030LC - 100 M

- (1)
- 2
- 3 4
- **1** Product Code
- 2 Dimensions Code
- **3 Inductance Code**
- **4** Tolerance Code

(1) SHAPES AND DIMENSIONS







A: 6.30 Max. mm
B: 6.20 Max. mm
C: 3.00 Max. mm
D: 4.80 Ref. mm
E: 0.60 Ref. mm
F: 2.00 Ref. mm
G: 6.40 Max. mm

(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L: HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

(3) CHARACTERISTICS

- (3)-1 Operate temperature range -40° C \sim +125 $^{\circ}$ C (Including self temp. rise)
- (3)-2 Storage temperature range -40° C $\sim +125^{\circ}$ C



TABLE 1

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated DC Current		Morking
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω) Max.	IDC1(A)	IDC2(A)	Marking
MSCDRI-6030LC-1R0□	1.0	N	100kHz/0.25V	14m	3.59	5.32	1R0
MSCDRI-6030LC-1R5□	1.5	N	100kHz/0.25V	16m	2.93	4.45	1R5
MSCDRI-6030LC-2R2□	2.2	N	100kHz/0.25V	20m	2.42	4.13	2R2
MSCDRI-6030LC-3R3□	3.3	N	100kHz/0.25V	26m	1.89	3.54	3R3
MSCDRI-6030LC-3R6□	3.6	N	100kHz/0.25V	26m	1.89	3.54	3R6
MSCDRI-6030LC-4R7□	4.7	N	100kHz/0.25V	33m	1.66	3.03	4R7
MSCDRI-6030LC-6R2□	6.2	N	100kHz/0.25V	39m	1.45	2.69	6R2
MSCDRI-6030LC-6R8	6.8	M,N	100kHz/0.25V	41m	1.40	2.60	6R8
MSCDRI-6030LC-8R2□	8.2	M,N	100kHz/0.25V	49m	1.20	2.50	8R2
MSCDRI-6030LC-100	10	M,N	100kHz/0.25V	59m	1.14	2.25	100
MSCDRI-6030LC-120	12	M,N	100kHz/0.25V	63m	1.04	2.12	120
MSCDRI-6030LC-150	15	M,N	100kHz/0.25V	75m	0.93	2.04	150
MSCDRI-6030LC-180	18	M,N	100kHz/0.25V	89m	0.85	1.86	180
MSCDRI-6030LC-220	22	M,N	100kHz/0.25V	0.115	0.77	1.58	220
MSCDRI-6030LC-270	27	M,N	100kHz/0.25V	0.144	0.70	1.35	270
MSCDRI-6030LC-330	33	M,N	100kHz/0.25V	0.168	0.63	1.19	330
MSCDRI-6030LC-390	39	M,N	100kHz/0.25V	0.180	0.58	1.16	390
MSCDRI-6030LC-470	47	M,N	100kHz/0.25V	0.225	0.53	1.05	470
MSCDRI-6030LC-560	56	M,N	100kHz/0.25V	0.264	0.48	0.97	560
MSCDRI-6030LC-680	68	M,N	100kHz/0.25V	0.324	0.44	0.87	680
MSCDRI-6030LC-820	82	M,N	100kHz/0.25V	0.396	0.40	0.76	820
MSCDRI-6030LC-101	100	M,N	100kHz/0.25V	0.498	0.36	0.69	101
MSCDRI-6030LC-151	150	M,N	100kHz/0.25V	0.738	0.31	0.52	151
MSCDRI-6030LC-221	220	M,N	100kHz/0.25V	1.400	0.28	0.45	221
MSCDRI-6030LC-331	330	M,N	100kHz/0.25V	2.100	0.18	0.42	331

[※] ☐ specify the inductance tolerance,M(±20%),N(±30%)

% IDC1 : Based on inductance change (\triangle L/Lo : drop 30% Max.) @ambient temperature : 25 $^{\circ}$ C

IDC2: Based on temperature rise ($\triangle T:40^{\circ}C$ TYP.)

Rated DC Current: The less value which is IDC1 or IDC2.



(4) RELIABILITY TEST METHOD MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS			
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		in figure 1 and a load applied unitil the figure in the arrow			
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)			
	no mechanical	PCB dimension shall the page 7/9			
	damage or elec-	F(Pressurization)			
	trical damage.	\Box			
		R5 45±2 45±2 10 20 R340			
		PRESSURE ROD figure-1			
Vibration	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		and when a vibration having an amplitude of 1.52mm			
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should			
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.			
	damage.	(A total of 6 hours)			
Solderability	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated			
	More than 90%	over the whole of the sample before hard, the sample shall			
		then be preheated for about 2 minutes in a temperature of			
		130∼150℃ and after it has been immersed to a depth 0.5mm			
		below for 3±0.2 seconds fully in molten solder M705 with			
		a temperature of 245±5℃.			
		More than 90% of the electrode sections shall be couered			
		with new solder smoothly when the sample is taken out of			
		the solder bath.			



MECHANICAL

TEST ITEM		SPECIFICATION					
TEST ITEM Resistance to Soldering heat (reflow soldering)	There shall be no damage or problems.	Temperature profile of reflow soldering soldering (Peak temperature 260±3°C 10 sec 150 Pre-heating Pre-heating Slow cooling (Stored at room temperature) 2 min 100 2 min 100 2 min 2 min. or more					
		The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time. The specimen shall be stored at standard atmospheric conditions for 1 hour, after which the measurement shall be made.					

ELECTRICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Insulation	There shall be	DC 100V voltage shall be applied across this sample of top
resistance	no other	surface and the terminal.
	damage or	The insulation resistance shall be more than $1 \times 10^8 \Omega$.
	problems.	
Dielectric	There shall be	AC 100V voltage shall be applied for 1 minute acrosset the top
withstand	no other	surface and the terminal of this sample
voltage	damage or	
	problems.	
Temperature	∆L/L20°C ≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85℃,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be △L/L20℃≦±10%.



ENVIROMENT CHARACTERISTICS

TEST ITEM				SPECIFICATION			
High temperature	∆L/Lo≦±5%	The samp	The sample shall be left for 96±4 hours in an atmospere with				
storage		a tempera	a temperature of 85±2℃ and a normal humidity.				
	There shall be	Upon con	Upon completion of the measurement shall be made after the				
	no mechanical	sample h	sample has been left in a normal temperature and normal				
	damage.	humidity	humidity for 1 hour.				
Low temperature	∆L/Lo≦±5%	The samp	The sample shall be left for 96±4 hours in an atmosphere with				
storage		a tempera	a temperature of -25±3℃.				
	There shall be	Upon con	Upon completion of the test, the measurement shall be made				
	no mechanical	after the	after the sample has been left in a normal temperature and				
	damage.	normal h	normal humidity for 1 hour.				
Change of	∆L/Lo≦±5%	The samp	The sample shall be subject to 5 continuos cycles, such as shown				
temperature		in the tab	le 2	below and then it shall b	oe subjected to standa	ırd	
	There shall be	atmosphe	eric (conditions for 1 hour, af	ter which measureme	nt	
	no other dama-	shall be n	nade) .			
	ge of problems						
		_	table 2				
				Temperature	Duration		
			1	−25±3 ℃	30 min.		
				(Themostat No.1)			
			2	Standard	No.1→No.2		
				atmospheric			
			3	85±2 ℃	30 min.		
				(Themostat No.2)			
			4	Standard	No.2→No.1		
				atmospheric			
Moisture storage	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in a temperature of					
		40±2℃ and a humidity(RH) of 90∼95%.					
	There shall be	Upon completion of the test, the measurement shall be made					
	no mechanical	after the sample has been left in a normal temperature and					
	damage.	normal h	normal humidity more than 1 hour.				
Test conditions :	•						
The s	sample shall be reflo	w soldered o	onto	the printed circuit board	d in every test.		

The sample shall be reflow soldered onto the printed circuit board in every test.

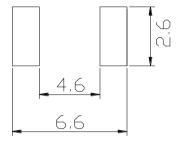


(5) LAND DIMENSION (Ref.)

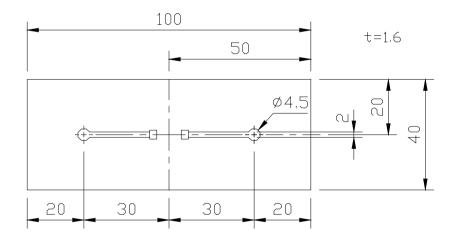
PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN) Unit: mm

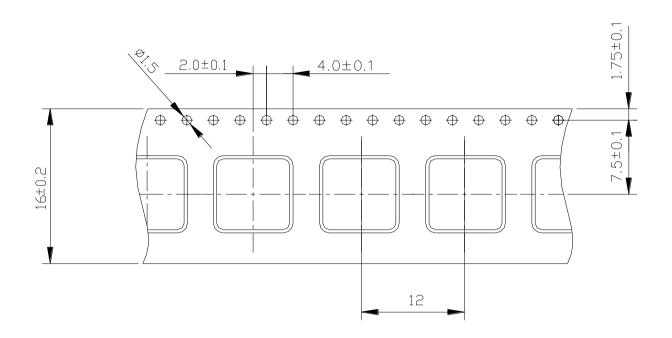


(5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD

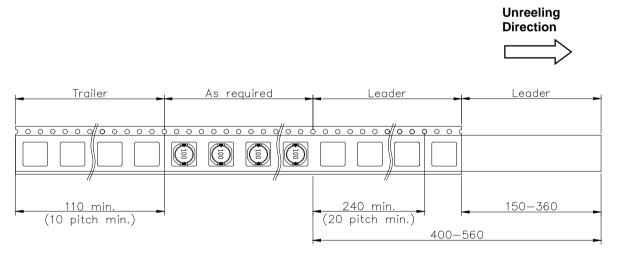


(6) PACKAGING

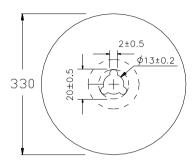
(6)-1 CARRIER TAPE DIMENSIONS (mm)

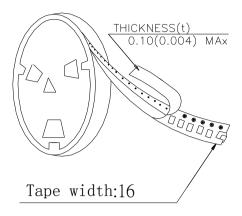


(6)-2 TAPING DIMENSIONS (mm)



(6)-3 REEL DIMENSIONS (mm)





(6)-4 QUANTITY

1500pcs/Reel

The products are packaged so that no damage will be sustained.